12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250226002.1
Qualification of FFAB using qualified Process Technology, Die Revision, Datasheet, and additional Assembly BOM options for select devices
Change Notification / Sample Request

Date: February 26, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 60 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

Changes outlined in this notification underscore our commitment to product longevity and supply continuity, as well as our continued efforts to transition to newer, more efficient manufacturing processes and technologies. Specifically, this particular notification is related to TI's multiyear transition plan for our two remaining 150-millimeter production lines (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). SFAB closure activities are expected to begin by the end of 2025. DFAB will remain open with a smaller set of 200mm technologies and GaN.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Change Management Team
SC Business Services

20250226002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA4830IPWR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250226002.1	PCN Date:	February 26, 2025
Title:	Qualification of FFAB using qualified Process Technology, Die Revision, Datasheet, and additional Assembly BOM options for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	May 27, 2025	Sample requests accepted until:	April 27, 2025*

***Sample requests received after April 27, 2025 will not be supported.**

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

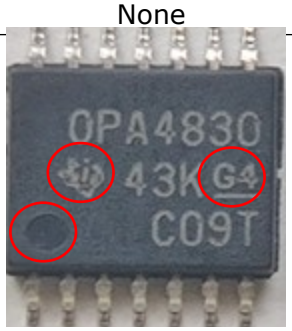
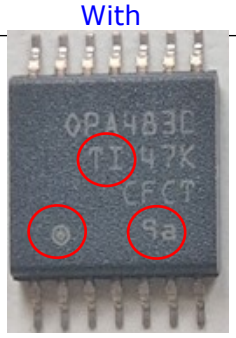
Description of Change:

Texas Instruments is pleased to announce the qualification of its FFAB fabrication facility as an additional Wafer Fab option in addition to Assembly BOM options for the devices listed below.

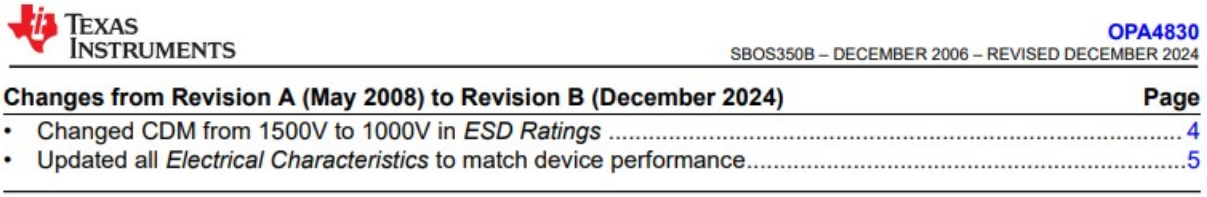
Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
SFAB	CBC10	150 mm	FFAB	BICOMHD	200 mm

The die was also changed as a result of the process change.

Construction differences are as follows:

	Current	New
Wire diam/type	0.96mil Au	1.0mil Cu
ECAT	Include Value	Remove
TI Bug	Include	Replace with "TI" text
Pin 1 ID	Embossed	Dot
Mold Unit ID	None	With
Example		

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



TEXAS INSTRUMENTS

OPA4830

SBOS350B – DECEMBER 2006 – REVISED DECEMBER 2024

Changes from Revision A (May 2008) to Revision B (December 2024) **Page**

- Changed CDM from 1500V to 1000V in *ESD Ratings* 4
- Updated all *Electrical Characteristics* to match device performance..... 5

Product	Current	New	Link to full datasheet

Folder	Datasheet Number	Datasheet Number	
OPA4830	SBOS350A	**SBOS350B**	http://www.ti.com/product/OPA4830

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
FR-BIP-1	**TID**	**DEU**	**Freising**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
C	**A**

Sample product shipping label (not actual product label)

Product Affected:

OPA4830IPWR

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: OPA4830IPWR	QBS Product Reference: OPA2830IDR	QBS Product Reference: OPA2830IDGKR	QBS Process Reference: THS3491IDDAR	QBS Process Reference: OPA2810IDGKR	QBS Package Reference: SN3257QPWRQ1	QBS Package Reference: OPA4991QPWRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	-	-	1/77/0
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	-	3/231/0	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	3/231/0	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	3/231/0	3/231/0	-	-
TC	A4	Temperature Cycle	-55/150C	1000 Cycles	-	-	-	-	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	3/231/0	3/231/0	-	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	1/45/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	3/231/0	3/231/0	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	3/135/0	-

Type	#	Test Name	Condition	Duration	Qual Device: OPA4830IPWR	QBS Product Reference: OPA2830IDR	QBS Product Reference: OPA2830IDGKR	QBS Process Reference: THS3491IDDAR	QBS Process Reference: OPA2810IDGKR	QBS Package Reference: SN3257QPWRQ1	QBS Package Reference: OPA4991QPWRQ1
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	3/231/0	3/231/0
HTOL	B1	Life Test	70C Vcc Max (self heating brings Tj up to 150C)	300 Hours	-	-	-	3/231/0	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/3000/0	-	-
ELFR	B2	Early Life Failure Rate	70C (self heating brings Tj up to 150C)	24 Hours	-	-	-	3/3000/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/15/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	3/30/0	1/10/0
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	1/3/0	3/9/0	3/9/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	3/9/0	3/9/0	-	-
ESD	E2	ESD HBM	-	4000 Volts	-	-	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	5000 Volts	-	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	-	3/18/0	3/9/0	1/6/0	3/18/0

Type	#	Test Name	Condition	Duration	Qual Device: OPA4830IPWR	QBS Product Reference: OPA2830IDR	QBS Product Reference: OPA2830IDGKR	QBS Process Reference: THS3491IDDAR	QBS Process Reference: OPA2810IDGKR	QBS Package Reference: SN3257QPWRQ1	QBS Package Reference: OPA4991QPWRQ1
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	1/30/0	3/90/0	3/90/0	3/90/0	3/90/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device OPA4830IPWR is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-NPD-2402-152

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.